

I claim:

1(amended). A mechanical apparatus comprising an enclosure [configured for receiving at least one electronic device], wherein the enclosure includes a plurality of elements providing a means of support or attachment to a means of external support.

5(amended). A mechanical apparatus comprising an enclosure with inter-connectible elements wherein each element means is capable of fitting within or mating with elements of [the first] other enclosure elements providing connection between enclosures.

**Remarks:**

Applicant has amended Claims 1 and 5 to more particularly define the invention in a patentable manner over the cited prior art. Claim 5 is further amended to be more clear in language as per section 112. Furthermore, prior art cited (Patent #6,297,548) claims show how the semiconductor (electronic) device inside the chip package is mounted to the enclosure, whereas Applicants claims are for how the mechanical enclosure is mounted to external structures such as walls, panels, DIN rails and other enclosures. The prior art does not demonstrate any ability to mount to such surfaces, as it is impossible and impractical to mount a BGA chip to such surfaces, as this would defeat the function of such a chip, nor does prior art mention more than one method of stacking. Prior art only demonstrates basic stacking, just like a Lego. Claim 1 does not refer to the ability to stack the invention, but how to mount it to various useable surfaces, which no prior art references.

Prior art also does not allow for the disassembly, since the part is hermetically sealed. The claimed invention is able to be disassembled and reassembled an infinite number of times.